

ABSTRACT OF THE DISCLOSURE

In a laminated ceramic electronic component, the sectional size of via-hole conductors extending through thicker ceramic layers is larger than that of via-hole conductors extending through thinner ceramic layers. This makes it possible to facilitate filling of a conductive paste for the via-hole conductors having a larger height and to inhibit a conductive paste for the via-hole conductors having a smaller height from being lost after filling.

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